



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Keith E. FOGEL et al. CONFIRM. NO.: 6557  
SERIAL NO.: 10/815,103 ART UNIT: 2826  
FILED: 03/31/2004 EXAMINER: L. ANDUJAR  
TITLE: INTERCONNECTIONS FOR FLIP-CHIP USING LEAD-FREE  
SOLDERS AND HAVING REACTION BARRIER LAYERS  
ATTORNEY DOCKET NO.: YOR920030190US1

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

TRANSMITTAL OF FORMAL DRAWINGS

Sir:

Enclosed are three sheets of formal drawings to  
replace the informal drawings currently on file.

Respectfully submitted,

David Aker  
David Aker, Reg. No. 29,277  
23 Southern Road  
Hartsdale, NY 10530

4/30/2007  
Date

Tel. & Fax 914 674-1094

Certificate of Mailing

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first  
class mail in an envelope addressed to: Commissioner for  
Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

April 30, 2007  
Date

David Aker  
Name of Person Making Deposit